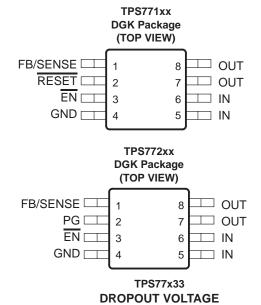
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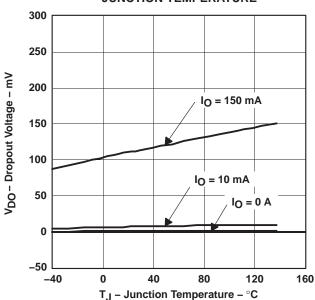
- Qualified for Automotive Applications
- Open Drain Power-On Reset With 220-ms Delay (TPS771xx)
- Open Drain Power-Good (PG) Status Output (TPS772xx)
- 150-mA Low-Dropout Voltage Regulator
- Available in 1.5-V, 1.8-V, 2.7-V, 2.8-V, 3.3-V,
   5.0-V Fixed Output and Adjustable Versions
- Dropout Voltage Typically 115 mV at 150 mA (TPS77133, TPS77233)
- Ultralow 92-μA Quiescent Current (Typ)
- 8-Pin MSOP (DGK) Package
- Low Noise (55 μV<sub>rms</sub>) Without External Filter (Bypass) Capacitor (TPS77118, TPS77218)
- 2% Tolerance Over Specified Conditions for Fixed-Output Versions
- Fast Transient Response
- Thermal Shutdown Protection

#### description

The TPS771xx and TPS772xx are low-dropout regulators with integrated power-on reset and power good (PG) function respectively. These devices are capable of supplying 150 mA of output current with a dropout of 115 mV (TPS77133, TPS77233). Quiescent current is 92 μA at full load dropping down to 1 µA when device is disabled. These devices are optimized to be stable with a wide range of output capacitors including low ESR ceramic (10 μF) or low capacitance (1 μF) tantalum capacitors. These devices have extremely low noise output performance (55 μV<sub>rms</sub>) without using any added filter capacitors. TPS771xx and TPS772xx are designed to have fast transient response for larger load current changes.



vs JUNCTION TEMPERATURE



The TPS771xx or TPS772xx is offered in 1.5 V,1.8-V, 2.7-V, 2.8-V, 3.3-V, and 5 V fixed-voltage versions and in an adjustable version (programmable over the range of 1.5 V to 5.5 V). Output voltage tolerance is 2% over line, load, and temperature ranges. The TPS771xx and TPS772xx families are available in 8-pin MSOP (DGK) packages.



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#### description (continued)

Because the PMOS device behaves as a low-value resistor, the dropout voltage is low (typically 115 mV at an output current of 150 mA for 3.3-V option) and is directly proportional to the output current. Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is low and independent of output loading (typically 92 µA over the full range of output current, 0 mA to 150 mA). These two key specifications yield a significant improvement in operating life for battery-powered systems.

The device is enabled when the  $\overline{\rm EN}$  pin is connected to a low-level input voltage. This LDO family also features a sleep mode; applying a TTL high signal to  $\overline{\text{EN}}$  (enable) shuts down the regulator, reducing the quiescent current to less than 1  $\mu$ A at  $T_{.1}$  = 25°C.

The TPS771xx features an integrated power-on reset, commonly used as a supply voltage supervisor (SVS) or reset output voltage. The RESET output of the TPS771xx initiates a reset in DSP, microcomputer or microprocessor systems at power up and in the event of an undervoltage condition. An internal comparator in the TPS771xx monitors the output voltage of the regulator to detect an undervoltage condition on the regulated output voltage. When OUT reaches 95% of its regulated voltage, RESET goes to a high-impedance state after a 220 ms delay. RESET goes to low-impedance state when OUT is pulled below 95% (i.e., over load condition) of its regulated voltage.

For the TPS772xx, the power good terminal (PG) is an active high output, which can be used to implement a power-on reset or a low-battery indicator. An internal comparator in the TPS772xx monitors the output voltage of the regulator to detect an undervoltage condition on the regulated output voltage. When OUT falls below 82% of its regulated voltage, PG goes to a low-impedance state. PG goes to a high-impedance state when OUT is above 82% of its regulated voltage.

#### **AVAILABLE OPTIONS**†‡§

_	OUTPUT VOLTAGE (V)		PACKAGED DEVICES <sup>‡</sup> MSOP (DGK)							
TJ	TYP		TPS771xx SYMBOL		TPS772xx SYMBOL					
	5	TPS77150QDGKQ1§	BMO	TPS77250QDGKQ1§	BMI					
	3.3	TPS77133QDGKQ1§	BMN	TPS77233QDGKQ1§	BMH					
	2.8	TPS77128QDGKQ1§	BMM	TPS77228QDGKQ1§	BMG					
-40°C to 125°C	2.7	TPS77127QDGKQ1§	BML	TPS77227QDGKQ1§	BMF					
-40 0 10 123 0	1.8	TPS77118QDGKQ1§	BMK	TPS77218QDGKQ1§	BME					
	1.5	TPS77115QDGKQ1§	BMJ	TPS77215QDGKQ1§	BMD					
	Adjustable 1.5 V to 5.5 V	TPS77101QDGKQ1	ANP	TPS77201QDGKQ1§	ВМС					

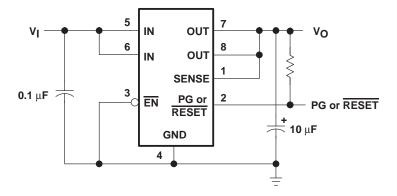
<sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

NOTE: The TPS77101 and TPS77201 are programmable using an external resistor divider (see the application information section). The DGK package is available taped and reeled. Add an R suffix to the device type (e.g., TPS77101QDGKRQ1).



<sup>‡</sup> Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

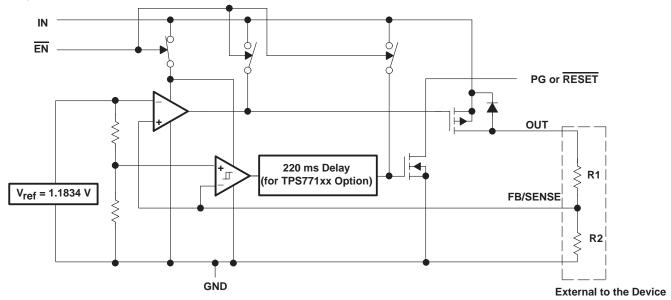
<sup>§</sup> Product Preview



**Figure 1. Typical Application Configuration (For Fixed Output Options)** 

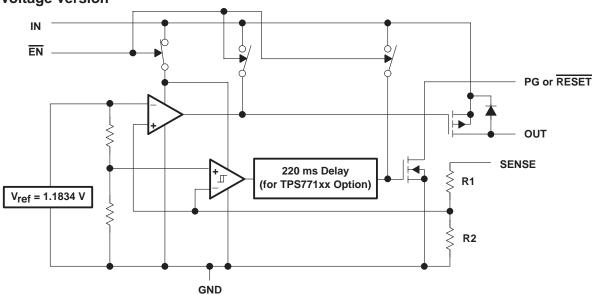
### functional block diagrams

#### adjustable version



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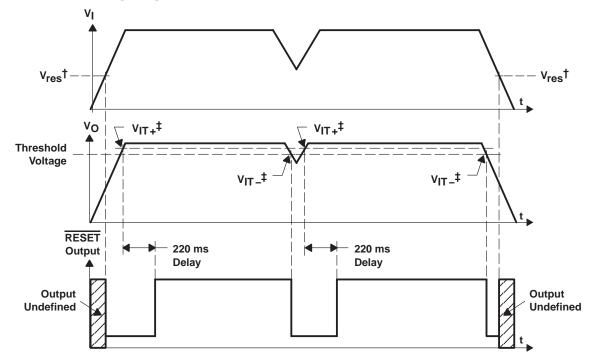
#### fixed-voltage version



#### **Terminal Functions**

TERMIN	TERMINAL		DECORPTION
NAME	NO.	1/0	DESCRIPTION
TPS771XX			
FB/SENSE	1	I	Feedback input voltage for adjustable device (sense input for fixed options)
RESET	2	0	Reset output
EN	3	I	Enable input
GND	4		Regulator ground
IN	5, 6	I	Input voltage
OUT	7, 8	0	Regulated output voltage
TPS772XX			
FB/SENSE	1	I	Feedback input voltage for adjustable device (sense input for fixed options)
PG	2	0	Power good
EN	3	I	Enable input
GND	4		Regulator ground
IN	5, 6	Ī	Input voltage
OUT	7, 8	0	Regulated output voltage

### **TPS771xx RESET** timing diagram



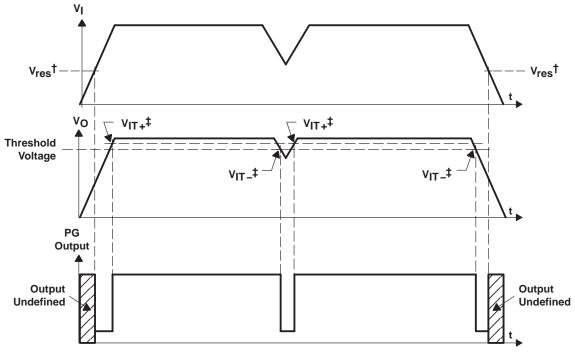
 $<sup>^\</sup>dagger V_{\text{res}}$  is the minimum input voltage for a valid  $\overline{\text{RESET}}$ . The symbol  $V_{\text{res}}$  is not currently listed within EIA or JEDEC standards for semiconductor symbology.



<sup>‡</sup> V<sub>IT</sub> – Trip voltage is typically 5% lower than the output voltage (95%V<sub>O</sub>) V<sub>IT</sub> to V<sub>IT</sub> is the hysteresis voltage.

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#### TPS772xx PG timing diagram



<sup>†</sup> V<sub>res</sub> is the minimum input voltage for a valid PG. The symbol V<sub>res</sub> is not currently listed within EIA or JEDEC standards for semiconductor symbology.

### absolute maximum ratings over operating junction temperature range (unless otherwise noted)†

Input voltage range, V <sub>I</sub> , (see Note 1)	
Voltage range at EN	
Maximum RESET voltage (TPS771xx)	16.5 V
Maximum PG voltage (TPS772xx)	16.5 V
Peak output current	Internally limited
Continuous total power dissipation	See Dissipation Rating Table
Output voltage, V <sub>O</sub> (OUT, FB)	5.5 V
Operating virtual junction temperature range, T <sub>J</sub>	–40°C to 125°C
Storage temperature range, T <sub>stq</sub>	65°C to 150°C
ESD rating, HBM	2 kV

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to network terminal ground.



<sup>&</sup>lt;sup>‡</sup> V<sub>IT</sub> – Trip voltage is typically 18% lower than the output voltage (82%V<sub>O</sub>) V<sub>IT</sub> to V<sub>IT</sub> is the hysteresis voltage.

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#### **DISSIPATION RATING TABLE - FREE-AIR TEMPERATURES**

PACKAGE	AIR FLOW (CFM)	θJA (°C/W)	θJC (°C/W)	T <sub>A</sub> < 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING
	0	266.2	3.84	376 mW	3.76 mW/°C	207 mW	150 mW
DGK	150	255.2	3.92	392 mW	3.92 mW/°C	216 mW	157 mW
	250	242.8	4.21	412 mW	4.12 mW/°C	227 mW	165 mW

#### recommended operating conditions

	MIN	MAX	UNIT
Input voltage, VI <sup>†</sup>	2.7	10	V
Output voltage range, VO	1.5	5.5	V
Output current, IO (see Note 2)	0	150	mA
Operating virtual junction temperature, T <sub>J</sub> (see Note 2)	-40	125	°C

<sup>†</sup> To calculate the minimum input voltage for your maximum output current, use the following equation:  $V_{I(min)} = V_{O(max)} + V_{DO(max load)}$ .

NOTE 2: Continuous current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.

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electrical characteristics over recommended operating junction temperature range (-40°C to 125°C),  $V_I = V_{O(tvp)} + 1 V$ ,  $I_O = 1 \text{ mA}$ ,  $\overline{EN} = 0 V$ ,  $C_O = 10 \mu F$  (unless otherwise noted)

PARAME	TER	TEST CON	DITIONS	MIN	TYP	MAX	UNIT		
		$1.5 \text{ V} \le \text{V}_{\text{O}} \le 5.5 \text{ V},$	T <sub>J</sub> = 25°C		Vo				
	Adjustable voltage	$1.5 \text{ V} \le \text{V}_{\text{O}} \le 5.5 \text{ V}$		0.98V <sub>O</sub> 1.02V		1.02V <sub>O</sub>	V		
		T <sub>J</sub> = 25°C,	2.7 V < V <sub>IN</sub> < 10 V		1.5				
	1.5-V Output	2.7 V < V <sub>IN</sub> < 10 V		1.47		1.53			
	40000	T <sub>J</sub> = 25°C,	2.8 V < V <sub>IN</sub> < 10 V		1.8				
	1.8-V Output	2.8 V < V <sub>IN</sub> < 10 V		1.764		1.836			
Output voltage	0.7.1/ Output	T <sub>J</sub> = 25°C,	3.7 V < V <sub>IN</sub> < 10 V		2.7		.,		
(see Note 3 and Note 4)	2.7-V Output	3.7 V < V <sub>IN</sub> < 10 V		2.646		2.754	V		
	0.0.1/ Outrait	$T_J = 25^{\circ}C$ ,	3.8 V < V <sub>IN</sub> < 10 V		2.8				
	2.8-V Output	3.8 V < V <sub>IN</sub> < 10 V		2.744		2.856			
	0.0.1/ Outroot	T <sub>J</sub> = 25°C,	4.3 V < V <sub>IN</sub> < 10 V		3.3				
	3.3-V Output	4.3 V < V <sub>IN</sub> < 10 V		3.234		3.366			
	E V Outrout	$T_J = 25^{\circ}C$ ,	6 V < V <sub>IN</sub> < 10 V		5		V		
	5-V Output	6 V < V <sub>IN</sub> < 10 V		4.9		5.1	V		
Quiescent current (GND curre	ent) (see Note 3 and	T <sub>J</sub> = 25°C			92				
Note 4)						125	μΑ		
Output valtage line regulation	(A)(= A(=) (ooo Note E)	$V_{O} + 1 V < V_{I} \le 10 V$ ,	T <sub>J</sub> = 25°C		0.005		%/V		
Output voltage line regulation	(\(\text{\text{\$\sigma}\$	$V_{O} + 1 V < V_{I} \le 10 V$				0.05	%/V		
Load regulation		T <sub>J</sub> = 25°C			1		mV		
Output noise voltage		BW = 300 Hz to 100 kHz TPS77118, TPS77218	$z, T_J = 25^{\circ}C,$		55		μVrms		
Output current Limit		VO = 0 V			0.9	1.4	Α		
Peak output current		2-ms pulse width,	50% duty cycle		400		mA		
Thermal shutdown junction te	mperature				144		°C		
Otan dha assassa		EN = VI,	T <sub>J</sub> = 25°C			1	μΑ		
Standby current		EN = VI				3	μΑ		
FB input current	Adjustable voltage	FB = 1.5 V				1	μΑ		
High level enable input voltag	е			2			V		
Low level enable input voltage	е					0.7	V		
Enable input current				-1.5		1.5	μΑ		
Power supply ripple rejection	(TPS77118, TPS77218)	f = 1 KHz,	T <sub>J</sub> = 25°C		55		dB		

NOTES: 3. Minimum input operating voltage is 2.7 V or VO(typ) + 1 V, whichever is greater. Maximum input voltage = 10 V, minimum output

4. If 
$$V_O < 1.8 \text{ V then } V_{I(max)} = 10 \text{ V}, V_{I(min)} = 2.7 \text{ V}$$
:

Line regulation (mV) =  $(\%/V) \times \frac{V_O(V_{I(max)} - 2.7 \text{ V})}{100} \times 1000$ 

If  $V_O > 2.5 \text{ V then } V_{I(max)} = 10 \text{ V}, V_{I(min)} = Vo + 1 \text{ V}$ :

Line regulation (mV) = 
$$(\%/V) \times \frac{V_O(V_{I(max)} - (V_O + 1))}{100} \times 1000$$

5.  $I_0 = 1 \text{ mA to } 150 \text{ mA}$ 



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### electrical characteristics over recommended operating junction temperature range (–40°C to 125°C), $V_I = V_{O(typ)} + 1$ V, $I_O = 1$ mA, $\overline{EN} = 0$ V, $C_O = 10~\mu F$ (unless otherwise noted) (continued)

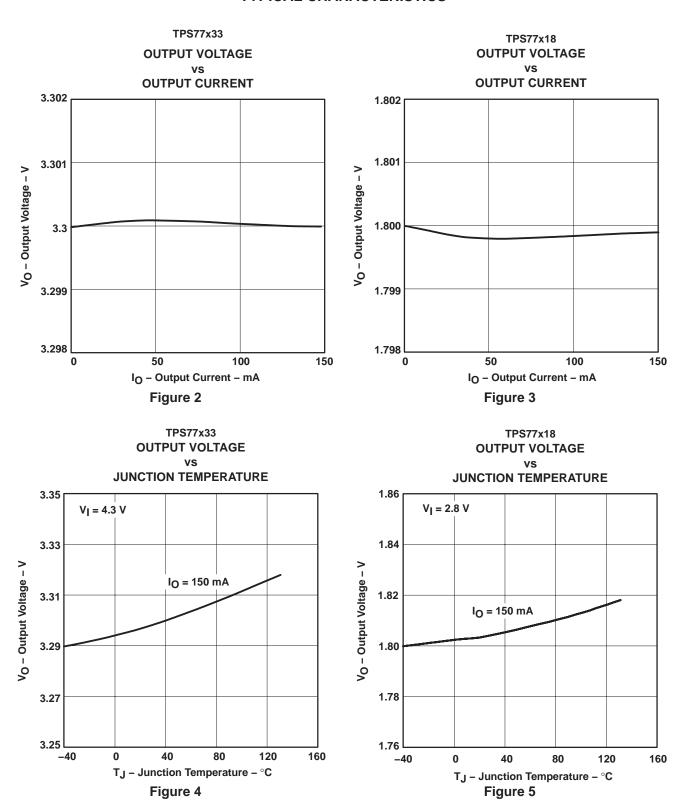
	PARAMETER		TEST CO	ONDITIONS	MIN	TYP	MAX	UNIT		
	Minimum input voltage for valid F	PG	$I(PG) = 300 \mu A$	V <sub>(PG)</sub> ≤ 0.8 V		1.1		V		
PG (TPS772xx)	Trip threshold voltage		V <sub>O</sub> decreasing		79		85	%VO		
	Hysteresis voltage		Measured at VO			0.5		%VO		
	Output low voltage		V <sub>I</sub> = 2.7 V,	$I_{(PG)} = 1mA$		0.15	0.4	V		
	Leakage current		V <sub>(PG)</sub> = 5 V				1	μΑ		
	Minimum input voltage for valid F	RESET	I(RESET) = 300 μ	ιA		1.1		V		
	Trip threshold voltage		VO decreasing		92		98	%VO		
Reset	Hysteresis voltage		Measured at VO			0.5		%Vo		
(TPS771xx)	Output low voltage		V <sub>I</sub> = 2.7 V,	I <sub>(RESET)</sub> = 1 mA		0.15	0.4	V		
	Leakage current		V <sub>(RESET)</sub> = 5 V				1	μΑ		
	RESET time-out delay					220		ms		
		0.0.1/.0.1	I <sub>O</sub> = 150 mA,	Г <sub>Ј</sub> = 25°С		150				
		2.8-V Output	I <sub>O</sub> = 150 mA,				265			
\/	Dunner truelte un (one Nate C)	2 2 1/ 0	I <sub>O</sub> = 150 mA,	I <sub>O</sub> = 150 mA, T <sub>J</sub> = 25°C		115		\/		
VDO	Dropout voltage (see Note 6)	3.3-V Output	I <sub>O</sub> = 150 mA				200	mV		
	5040		$I_0 = 150 \text{ mA},$		75					
		5.0-V Output	I <sub>O</sub> = 150 mA				115	5		

NOTE 6: IN voltage equals V<sub>O</sub>(typ) – 100 mV; 1.5 V, 1.8 V, and 2.7 V dropout voltage limited by input voltage range limitations (i.e., 3.3-V input voltage needs to drop to 3.2 V for purpose of this test).

#### TYPICAL CHARACTERISTICS

#### **Table of Graphs**

			FIGURE
.,		vs Output current	2, 3
VO	Output voltage	vs Junction temperature	4, 5
	Ground current	vs Junction temperature	6
	Power supply rejection ratio	vs Frequency	7
	Output spectral noise density	vs Frequency	8
Z <sub>O</sub>	Output impedance	vs Frequency	9
.,	5	vs Input voltage	10
$V_{DO}$	Dropout voltage	vs Junction temperature	11
	Line transient response		12, 14
	Load transient response		13, 15
	Output voltage and enable pulse	vs Time	16
	Equivalent series resistance (ESR)	vs Output current	18 – 21





#### **TYPICAL CHARACTERISTICS**

#### TPS77xxx GROUND CURRENT VS

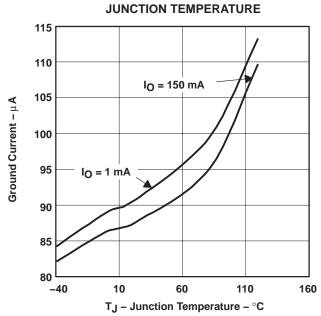
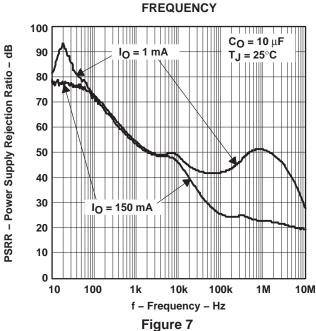
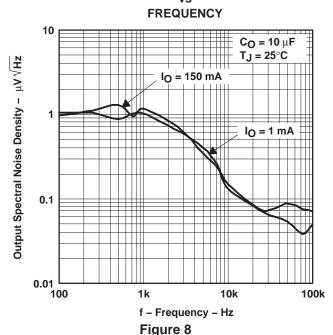


Figure 6

TPS77x33
POWER SUPPLY REJECTION RATIO
vs



TPS77x33
OUTPUT SPECTRAL NOISE DENSITY



TPS77x33
OUTPUT IMPEDANCE
vs
FREQUENCY

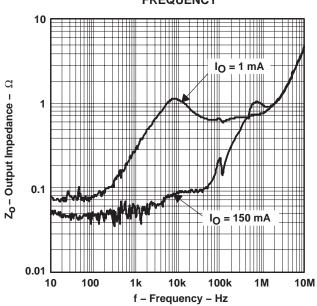
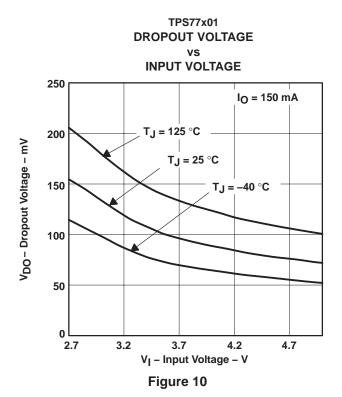
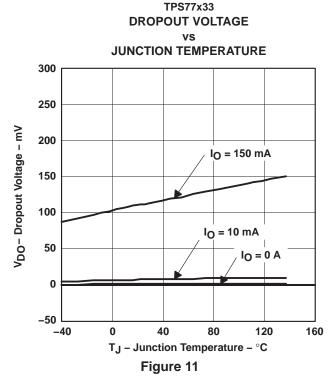


Figure 9







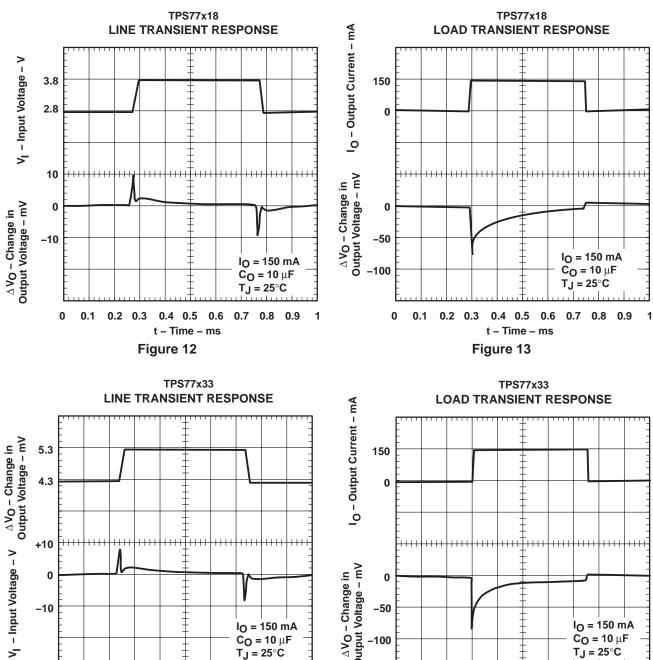


Figure 14

0.2 0.3

0.4 0.5 0.6

t - Time - ms

0.7 0.8 0.9

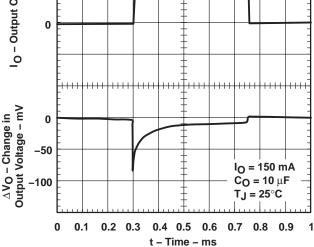


Figure 15



TPS77x33 OUTPUT VOLTAGE AND ENABLE PULSE

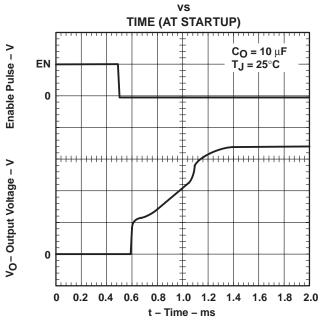


Figure 16

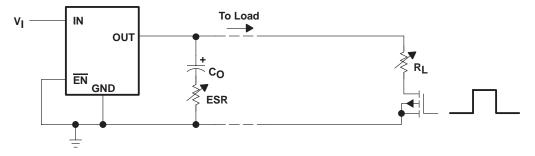
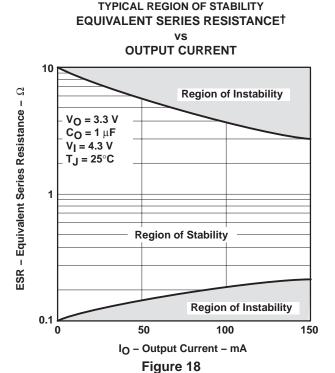
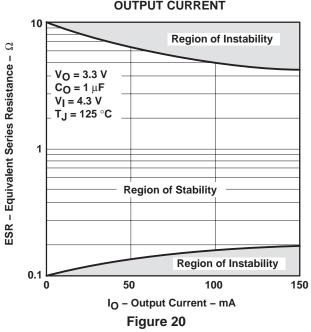


Figure 17. Test Circuit for Typical Regions of Stability (Figures 18 through 21) (Fixed Output Options)

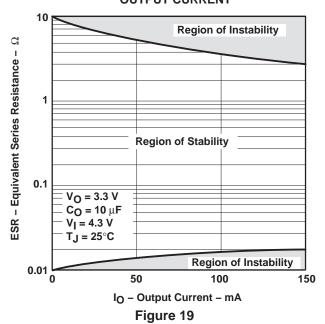
#### TYPICAL CHARACTERISTICS



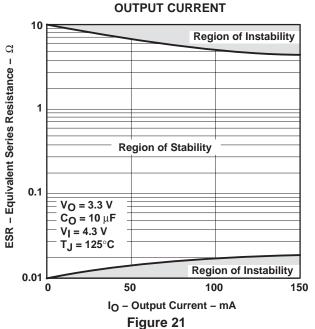
# TYPICAL REGION OF STABILITY EQUIVALENT SERIES RESISTANCE† vs OUTPUT CURRENT



# TYPICAL REGION OF STABILITY EQUIVALENT SERIES RESISTANCE† vs OUTPUT CURRENT



### TYPICAL REGION OF STABILITY EQUIVALENT SERIES RESISTANCE† vs



<sup>†</sup> Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to Co.



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#### APPLICATION INFORMATION

#### pin functions

#### enable (EN)

The  $\overline{\mathsf{EN}}$  terminal is an input which enables or shuts down the device. If  $\overline{\mathsf{EN}}$  is a logic high, the device will be in shutdown mode. When  $\overline{\mathsf{EN}}$  goes to logic low, then the device will be enabled.

#### power good (PG) (TPS772xx)

The PG terminal is an open drain, active high output that indicates the status of  $V_{out}$  (output of the LDO). When  $V_{out}$  reaches 82% of the regulated voltage, PG goes to a high-impedance state. It goes to a low-impedance state when  $V_{out}$  falls below 82% (i.e., over load condition) of the regulated voltage. The open drain output of the PG terminal requires a pullup resistor

#### sense (SENSE)

The SENSE terminal of the fixed-output options must be connected to the regulator output, and the connection should be as short as possible. Internally, SENSE connects to a high-impedance wide-bandwidth amplifier through a resistor-divider network and noise pickup feeds through to the regulator output. It is essential to route the SENSE connection in such a way to minimize/avoid noise pickup. Adding RC networks between the SENSE terminal and V<sub>out</sub> to filter noise is not recommended because it may cause the regulator to oscillate.

#### feedback (FB)

FB is an input terminal used for the adjustable-output options and must be connected to an external feedback resistor divider. The FB connection should be as short as possible. It is essential to route it in such a way to minimize/avoid noise pickup. Adding RC networks between FB terminal and V<sub>out</sub> to filter noise is not recommended because it may cause the regulator to oscillate.

#### reset (RESET) (TPS771xx)

The  $\overline{\text{RESET}}$  terminal is an open drain, active low output that indicates the status of  $V_{out}$ . When  $V_{out}$  reaches 95% of the regulated voltage,  $\overline{\text{RESET}}$  goes to a high-impedance state after a 220-ms delay.  $\overline{\text{RESET}}$  goes to a low-impedance state when  $V_{out}$  is below 95% of the regulated voltage. The open-drain output of the  $\overline{\text{RESET}}$  terminal requires a pullup resistor.



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#### **APPLICATION INFORMATION**

#### external capacitor requirements

An input capacitor is not usually required; however, a bypass capacitor (0.047  $\mu$ F or larger) improves load transient response and noise rejection if the TPS771xx or TPS772xx is located more than a few inches from the power supply. A higher-capacitance capacitor may be necessary if large (hundreds of milliamps) load transients with fast rise times are anticipated.

Most low noise LDOs require an external capacitor to further reduce noise. This impacts the cost and board space. The TPS771xx and TPS772xx have low noise specification requirements without using any external components.

Like all low dropout regulators, the TPS771xx or TPS772xx requires an output capacitor connected between OUT (output of the LDO) and GND (signal ground) to stabilize the internal control loop. The minimum recommended capacitance value is 1  $\mu$ F provided the ESR meets the requirement in Figure 19 and Figure 21. In addition, a low-ESR capacitor can be used if the capacitance is at least 10  $\mu$ F and the ESR meets the requirements in Figure 18 and Figure 20. Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described previously.

Ceramic capacitors have different types of dielectric material with each exhibiting different temperature and voltage variation. The most common types are X5R, X7R, Y5U, Z5U, and NPO. The NPO type ceramic type capacitors are generally the most stable over temperature. However, the X5R and X7R are also relatively stable over temperature (with the X7R being the more stable of the two) and are therefore acceptable to use. The Y5U and Z5U types provide high capacitance in a small geometry, but exhibit large variations over temperature; therefore, the Y5U and Z5U are not generally recommended for use on this LDO. Independent of which type of capacitor is used, you must make certain that at the worst case condition the capacitance/ESR meets the requirement specified in Figure 18 through Figure 21.



#### APPLICATION INFORMATION

Figure 22 shows the output capacitor and its parasitic impedances in a typical LDO output stage.

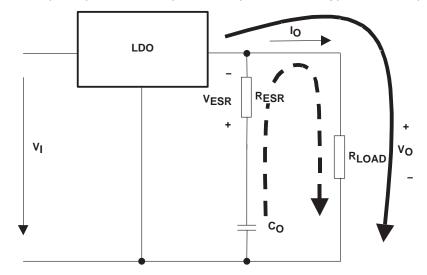


Figure 22. LDO Output Stage With Parasitic Resistances ESR and ESL

In steady state (dc state condition), the load current is supplied by the LDO (solid arrow) and the voltage across the capacitor is the same as the output voltage ( $V_{Cout} = V_{out}$ ). This means no current is flowing into the  $C_{out}$  branch. If  $I_{out}$  suddenly increases (transient condition), the following occurs:

- The LDO is not able to supply the sudden current need due to its response time (t<sub>1</sub> in Figure 23). Therefore, capacitor C<sub>out</sub> provides the current for the new load condition (dashed arrow). C<sub>out</sub> now acts like a battery with an internal resistance, ESR. Depending on the current demand at the output, a voltage drop will occur at R<sub>ESR</sub>. This voltage is shown as V<sub>ESR</sub> in Figure 22.
- When C<sub>out</sub> is conducting current to the load, initial voltage at the load will be V<sub>out</sub> = V<sub>Cout</sub> V<sub>ESR</sub>. Due to the discharge of C<sub>out</sub>, the output voltage V<sub>out</sub> drops continuously until the response time t<sub>1</sub> of the LDO is reached and the LDO resumes supplying the load. From this point, the output voltage starts rising again until it reaches the regulated voltage. This period is shown as t<sub>2</sub> in Figure 23.

The figure also shows the impact of different ESRs on the output voltage. The left brackets show different levels of ESRs where number 1 displays the lowest and number 3 displays the highest ESR.

From above, the following conclusions can be drawn:

- The higher the ESR, the larger the droop at the beginning of load transient.
- The smaller the output capacitor, the faster the discharge time and the bigger the voltage droop during the LDO response period.



#### **APPLICATION INFORMATION**

#### conclusion

To minimize the transient output droop, capacitors must have a low ESR and be large enough to support the minimum output voltage requirement.

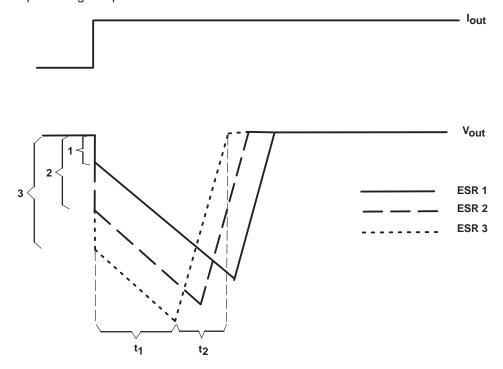


Figure 23. Correlation of Different ESRs and Their Influence to the Regulation of V<sub>out</sub> at a Load Step From Low-to-High Output Current

#### **APPLICATION INFORMATION**

#### programming the TPS77x01 adjustable LDO regulator

The output voltage of the TPS77x01 adjustable regulator is programmed using an external resistor divider as shown in Figure 24. The output voltage is calculated using:

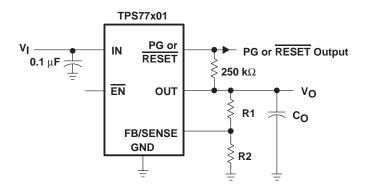
$$V_{O} = V_{ref} \times \left(1 + \frac{R1}{R2}\right) \tag{1}$$

Where:

 $V_{ref} = 1.1834 V typ (the internal reference voltage)$ 

Resistors R1 and R2 should be chosen for approximately 50- $\mu$ A divider current. Lower value resistors can be used but offer no inherent advantage and waste more power. Higher values should be avoided, as leakage currents at FB increase the output voltage error. The recommended design procedure is to choose R2 =  $30.1 \text{ k}\Omega$  to set the divider current at  $50 \text{ }\mu\text{A}$  and then calculate R1 using:

$$R1 = \left(\frac{V_{O}}{V_{ref}} - 1\right) \times R2 \tag{2}$$



### OUTPUT VOLTAGE PROGRAMMING GUIDE

OUTPUT VOLTAGE	R1	R2	UNIT
2.5 V	33.5	30.1	kΩ
3.3 V	53.8	30.1	kΩ
3.6 V	61.5	30.1	kΩ

NOTE: To reduce noise and prevent oscillation, R1 and R2 need to be as close as possible to the FB/SENSE terminal.

Figure 24. TPS77x01 Adjustable LDO Regulator Programming



#### APPLICATION INFORMATION

#### regulator protection

The TPS771xx or TPS772xx PMOS-pass transistor has a built-in back diode that conducts reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS771xx or TPS772xx also features internal current limiting and thermal protection. During normal operation, the TPS771xx or TPS772xx limits output current to approximately 0.9 A. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 150°C(typ), thermal-protection circuitry shuts it down. Once the device has cooled below 130°C(typ), regulator operation resumes.

#### power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of  $125^{\circ}$ C; the maximum junction temperature should be restricted to  $125^{\circ}$ C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation,  $P_{D(max)}$ , and the actual dissipation,  $P_{D}$ , which must be less than or equal to  $P_{D(max)}$ .

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_J max - T_A}{R_{\theta,IA}}$$

Where:

T<sub>.</sub>Imax is the maximum allowable junction temperature.

 $R_{\theta JA}$  is the thermal resistance junction-to-ambient for the package, i.e., 266.2°C/W for the 8-terminal MSOP with no airflow.

 $T_A$  is the ambient temperature.

The regulator dissipation is calculated using:

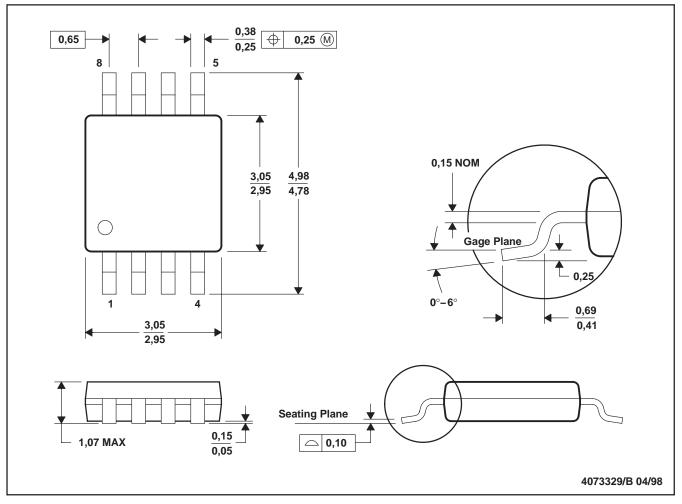
$$P_{D} = (V_{I} - V_{O}) \times I_{O}$$

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation triggers the thermal protection circuit.

#### **MECHANICAL DATA**

#### DGK (R-PDSO-G8)

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC MO-187



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#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
TPS77101QDGKRQ1	ACTIVE	VSSOP	DGK	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	ANP	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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### **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

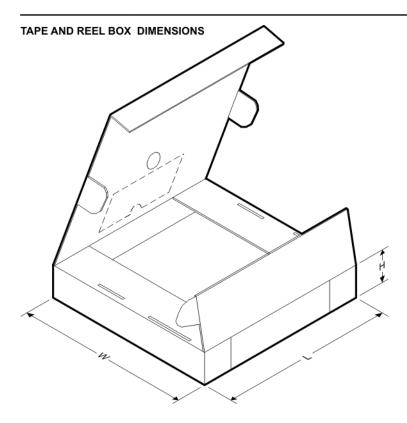


#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS77101QDGKRQ1	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS77101QDGKRQ1	VSSOP	DGK	8	2500	358.0	335.0	35.0



SMALL OUTLINE PACKAGE



#### NOTES:

PowerPAD is a trademark of Texas Instruments.

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-187.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
- 8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
- 9. Size of metal pad may vary due to creepage requirement.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 12. Board assembly site may have different recommendations for stencil design.



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